Tool ID: 502
Tool Location: 118

Equipment Information Sheet

E-Beam Lithography Hot Plates

Manager: Xinwei Wu 607-254-4934
Backup: Giovanni Sartorello 607-254-4853
Backup: John Treichler 607-254-4949

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Never set hot plates above 225C
- Always leave hot plates at their listed termperature
- Only use metal tweezers when removing samples

USAGE RESTRICTIONS

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 0 minutes

- If you need to use the hot plates for longer than 30 minutes contact staff first for approval

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- None

Last Updated: 05/30/2025